

带自动方向检测和 $\pm 15\text{kV}$ ESD 保护功能的 TXB0104 4 位双向电压电平转换器

1 特性

- A 端口支持 1.2V 至 3.6V 电压，B 端口支持 1.65V 至 5.5V 电压 ($V_{CCA} \leq V_{CCB}$)
- V_{CC} 隔离特性：如果任何一个 V_{CC} 输入接地 (GND)，则所有输出都处于高阻抗状态
- 以 V_{CCA} 为基准的输出使能 (OE) 输入电路
- 低功耗， I_{CC} 最大值为 $5\mu\text{A}$
- I_{OFF} 支持局部关断模式运行
- 闩锁性能超出 JESD 78 II 类规范要求的 100mA
- 静电放电 (ESD) 保护性能超过 JESD 22 规范的要求
 - A 端口：
 - 2500V 人体放电模型 (A114-B)
 - 1500V 充电器件模型 (C101)
 - B 端口：
 - $\pm 15\text{kV}$ 人体放电模型 (A114-B)
 - 1500V 充电器件模型 (C101)

2 应用

- 耳机
- 智能电话
- 平板电脑
- 台式计算机

3 说明

TXB0104 是一款采用两个独立可配置电源轨的 4 位同相转换器。A 端口设计用于跟踪 V_{CCA} 。 V_{CCA} 支持从 1.2V 到 3.6V 范围内的任一电源电压。B 端口设计用于跟踪 V_{CCB} 。 V_{CCB} 支持从 1.65V 到 5.5V 范围内的任意电源电压。这使得该器件可在 1.2V、1.5V、1.8V、2.5V、3.3V 和 5V 电压节点之间任意进行通用低压双向转换。 V_{CCA} 不可超过 V_{CCB} 。

当输出使能端 (OE) 输入为低电平时，所有输出均处于高阻抗状态。为确保在上电或掉电期间均处于高阻抗状态，必须将 OE 通过下拉电阻接地。驱动器的拉电流能力决定该电阻的最小值。

TXB0104 器件被设计成 OE 输入电路由 V_{CCA} 供电。

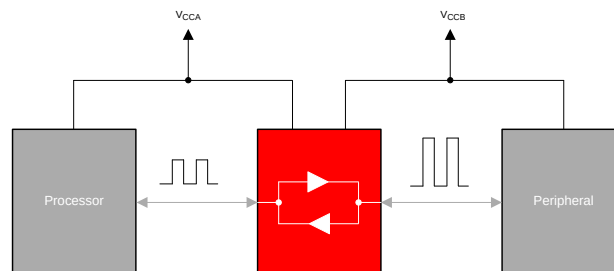
该器件完全适用于使用 I_{OFF} 的局部关断应用。 I_{OFF} 电路可禁用输出，以防在器件掉电时电流回流对器件造成损坏。

器件信息⁽¹⁾

器件型号	封装	封装尺寸 (标称值)
TXB0104RUT	UQFN (12)	2.00mm × 1.70mm
TXB0104D	SOIC (14)	8.65mm × 3.91mm
TXB0104ZXU/GXU	BGA MICROSTAR JUNIOR™(12)	2.00mm × 2.50mm
TXB0104PW	TSSOP (14)	5.00mm × 4.40mm
TXB0104RGY	VQFN (14)	3.50mm × 3.50mm
TXB0104YZT	DSBGA (12)	1.40mm × 1.90mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。

TXB010X 典型应用方框图



目录

1	特性	1	6.17	Operating Characteristics: $V_{CCA} = 1.8\text{ V to }3.3\text{ V}$, $V_{CCB} = 1.8\text{ V to }5\text{ V}$	12
2	应用	1	6.18	Typical Characteristics	13
3	说明	1	7	Parameter Measurement Information	14
4	修订历史记录	2	8	Detailed Description	16
5	Pin Configuration and Functions	3	8.1	Overview	16
6	Specifications	5	8.2	Functional Block Diagram	16
6.1	Absolute Maximum Ratings	5	8.3	Feature Description	17
6.2	ESD Ratings	5	8.4	Device Functional Modes	19
6.3	Recommended Operating Conditions	6	9	Application and Implementation	20
6.4	Thermal Information	6	9.1	Application Information	20
6.5	Electrical Characteristics	7	9.2	Typical Application	20
6.6	Timing Requirements: $V_{CCA} = 1.2\text{ V}$	8	10	Power Supply Recommendations	22
6.7	Timing Requirements: $V_{CCA} = 1.5\text{ V} \pm 0.1\text{ V}$	8	11	Layout	22
6.8	Timing Requirements: $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$	8	11.1	Layout Guidelines	22
6.9	Timing Requirements: $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$	8	11.2	Layout Example	22
6.10	Timing Requirements: $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$	8	12	器件和文档支持	23
6.11	Switching Characteristics: $V_{CCA} = 1.2\text{ V}$	9	12.1	接收文档更新通知	23
6.12	Switching Characteristics: $V_{CCA} = 1.5\text{ V} \pm 0.1\text{ V}$	9	12.2	社区资源	23
6.13	Switching Characteristics: $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$..	10	12.3	商标	23
6.14	Switching Characteristics: $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$..	10	12.4	静电放电警告	23
6.15	Switching Characteristics: $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$..	11	12.5	Glossary	23
6.16	Operating Characteristics: $V_{CCA} = 1.2\text{ V to }1.5\text{ V}$, $V_{CCB} = 1.5\text{ V to }1.8\text{ V}$	12	13	机械、封装和可订购信息	24

4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

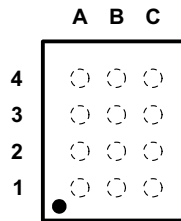
Changes from Revision H (January 2018) to Revision I	Page
• Updated <i>Pin Functions</i> table	4
• Added <i>Pin Assignments</i> table for GXU and ZXU package	4
• Added <i>Pin Assignments</i> table for YZT package	4
• Updated <i>Layout Example</i>	22

Changes from Revision G (November 2014) to Revision H	Page
• Added package families to package pinout drawings in <i>Pin Configuration and Functions</i> section	3
• Added junction temperature range in <i>Absolute Maximum Rating</i> table	5
• Changed unit from V to kV in <i>ESD Ratings</i> table	5

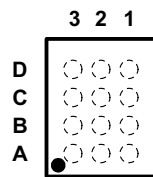
Changes from Revision F (May 2012) to Revision G	Page
• 已添加 引脚配置和功能部分，处理额定值表，特性 说明 部分、器件功能模式、应用和实施 部分、电源建议 部分、布局 部分、器件和文档支持 部分以及机械、封装和可订购信息 部分	1

5 Pin Configuration and Functions

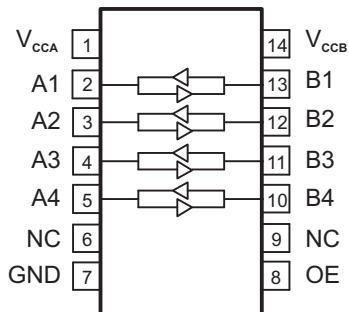
GXU and ZXU Package
12-Pin BGA Microstar Junior
Top View



YZT Package
12-Pin DSBGA
Top View

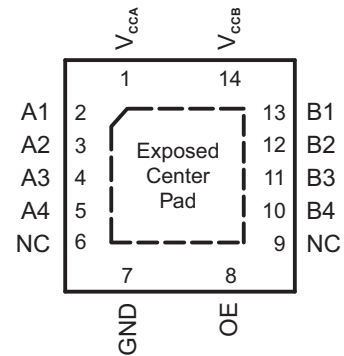


D or PW Package
14-Pin SOIC or TSSOP
Top View



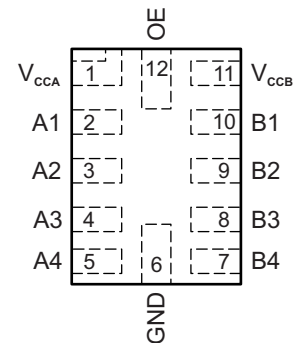
NC – No internal connection

RGY Package
14-Pin VQFN With Exposed Thermal Pad
Top View



NC – No internal connection

RUT Package
12-Pin UQFN
Top View



Pin Functions

NAME	PIN					I/O	DESCRIPTION
	D, PW	RGY	RUT	GXU, ZXU	YZT		
A1	2	2	2	A1	A3	I/O	Input/output 1. Referenced to V_{CCA} .
A2	3	3	3	A2	B3	I/O	Input/output 2. Referenced to V_{CCA} .
A3	4	4	4	A3	C3	I/O	Input/output 3. Referenced to V_{CCA} .
A4	5	5	5	A4	D3	I/O	Input/output 4. Referenced to V_{CCA} .
B1	13	13	10	C1	A1	I/O	Input/output 1. Referenced to V_{CCB} .
B2	12	12	9	C2	B1	I/O	Input/output 2. Referenced to V_{CCB} .
B3	11	11	8	C3	C1	I/O	Input/output 3. Referenced to V_{CCB} .
B4	10	10	7	C4	D1	I/O	Input/output 4. Referenced to V_{CCB} .
GND	7	7	6	B4	D2	—	Ground
NC	6, 9	6,9	—	—	—	—	No connection. Not internally connected.
OE	8	8	12	B3	C2	I	Tri-state output-mode enable. Pull OE low to place all outputs in tri-state mode. Referenced to V_{CCA} .
V_{CCA}	1	1	1	B2	B2	—	A-port supply voltage $1.2\text{ V} \leq V_{CCA} \leq 3.6\text{ V}$ and $V_{CCA} \leq V_{CCB}$.
V_{CCB}	14	14	11	B1	A2	—	B-port supply voltage $1.65\text{ V} \leq V_{CCB} \leq 5.5\text{ V}$.
Thermal pad	—	—	—	—	—	—	For the RGY package, the exposed center thermal pad must either be connected to Ground or left electrically open.

Pin Assignments: GXU and ZXU Package

	A	B	C
4	A4	GND	B4
3	A3	OE	B3
2	A2	V_{CCA}	B2
1	A1	V_{CCB}	B1

Pin Assignments: YZT Package

	3	2	1
D	A4	GND	B4
C	A3	OE	B3
B	A2	V_{CCA}	B2
A	A1	V_{CCB}	B1

6 Specifications

6.1 Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Supply voltage, V_{CCA}		–0.5	4.6	V
Supply voltage, V_{CCB}		–0.5	6.5	
Input voltage, V_i	A port	–0.5	4.6	V
	B port	–0.5	6.5	
Voltage applied to any output in the high-impedance or power-off state, V_O	A port	–0.5	4.6	V
	B port	–0.5	6.5	
Voltage applied to any output in the high or low state, $V_O^{(2)}$	A port	–0.5	$V_{CCA} + 0.5$	V
	B port	–0.5	$V_{CCB} + 0.5$	
Input clamp current, I_{IK}	$V_i < 0$		–50	mA
Output clamp current, I_{OK}	$V_O < 0$		–50	mA
Continuous output current, I_O		–50	50	mA
Continuous current through V_{CCA} , V_{CCB} , or GND		–100	100	mA
Junction temperature range, T_J			150	°C
Storage temperature range, T_{stg}		–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The value of V_{CCA} and V_{CCB} are provided in the recommended operating conditions table.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$ Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	A port	±2.5	kV
	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	B port	±15	
	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	A port	±1.5	
	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	B port	±1.5	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

 over operating free-air temperature range (unless otherwise noted)⁽¹⁾⁽²⁾

				MIN	MAX	UNIT
V _{CCA}	Supply voltage			1.2	3.6	V
V _{CCB}	Supply voltage			1.65	5.5	
V _{IH}	High-level input voltage	Data inputs	V _{CCA} = 1.2 V to 3.6 V V _{CCB} = 1.65 V to 5.5 V	V _{CCI} × 0.65 ⁽³⁾	V _{CCI}	V
		OE	V _{CCA} = 1.2 V to 3.6 V V _{CCB} = 1.65 V to 5.5 V	V _{CCA} × 0.65	5.5	
V _{IL}	Low-level input voltage	Data inputs	V _{CCA} = 1.2 V to 5.5 V V _{CCB} = 1.65 V to 5.5 V	0	V _{CCI} × 0.35 ⁽³⁾	V
		OE	V _{CCA} = 1.2 V to 3.6 V V _{CCB} = 1.65 V to 5.5 V	0	V _{CCA} × 0.35	
V _O	Voltage applied to any output in the high-impedance or power-off state	A-port	V _{CCA} = 1.2 V to 3.6 V V _{CCB} = 1.65 V to 5.5 V	0	3.6	V
		B-port	V _{CCA} = 1.2 V to 3.6 V V _{CCB} = 1.65 V to 5.5 V	0	5.5	
Δt/Δv	Input transition rise or fall rate	A-port inputs	V _{CCA} = 1.2 V to 3.6 V V _{CCB} = 1.65 V to 5.5 V		40	ns/V
		B-port inputs	V _{CCA} = 1.2 V to 3.6 V	V _{CCB} = 1.65 V to 3.6 V	40	
				V _{CCB} = 4.5 V to 5.5 V	30	
T _A	Operating free-air temperature			–40	85	°C

 (1) The A and B sides of an unused data I/O pair must be held in the same state, that is, both at V_{CCI} or both at GND.

 (2) V_{CCA} must be less than or equal to V_{CCB} and must not exceed 3.6 V.

 (3) V_{CCI} is the supply voltage associated with the input port.

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TXB0104						UNIT
		D	GXU/ZXU	PW	RGY	RUT	YZT	
		14 PINS	12 PINS	14 PINS	14 PINS	12 PINS	12 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	90.7	127.1	121.0	52.8	119.8	89.2	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	50.5	92.8	50.0	67.7	42.6	0.9	
R _{θJB}	Junction-to-board thermal resistance	45.4	62.2	62.8	28.9	52.5	14.4	
ψ _{JT}	Junction-to-top characterization parameter	14.7	2.3	6.4	2.6	0.7	3.0	
ψ _{JB}	Junction-to-board characterization parameter	45.1	62.2	62.2	29.0	52.3	14.4	
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	—	—	—	—	—	—	

 (1) For more information about traditional and new thermal metrics, see the [IC Package Thermal Metrics](#) application report.

6.5 Electrical Characteristics⁽¹⁾⁽²⁾

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CCA}	V _{CCB}	T _A = 25°C			–40°C to 85°C		UNIT
					MIN	TYP	MAX	MIN	MAX	
V _{OHA}	Port A output high voltage	I _{OH} = –20 μA	1.2 V		1.1			V _{CCA} – 0.4		V
			1.4 V to 3.6 V							
V _{OLA}	Port A output low voltage	I _{OL} = 20 μA	1.2 V		0.3			0.4		V
			1.4 V to 3.6 V							
V _{OHB}	Port B output high voltage	I _{OH} = –20 μA		1.65 V to 5.5 V				V _{CCB} – 0.4		V
V _{OLB}	Port B output low voltage	I _{OL} = 20 μA		1.65 V to 5.5 V				0.4		V
I _I	Inflection-point current	OE: V _I = V _{CCI} or GND	1.2 V to 3.6 V	1.65 V to 5.5 V	–1		1	–2	2	μA
I _{off}	Off-state current	A port: V _I or V _O = 0 to 3.6 V	0 V	0 V to 5.5 V	–1		1	–2	2	μA
		B port: V _I or V _O = 0 to 5.5 V	0 V to 3.6 V	0 V	–1		1	–2	2	
I _{OZ}	High-impedance-state output current	A or B port: OE = GND	1.2 V to 3.6 V	1.65 V to 5.5 V	–1		1	–2	2	μA
I _{CCA}	V _{CCA} supply current	V _I = V _{CCI} or GND I _O = 0	1.2 V	1.65 V to 5.5 V	0.06			5 2 –2		μA
			1.4 V to 3.6 V	1.65 V to 5.5 V						
			3.6 V	0 V						
			0 V	5.5 V						
I _{CCB}	V _{CCB} supply current	V _I = V _{CCI} or GND I _O = 0	1.2 V	1.65 V to 5.5 V	3.4			5 –2 2		μA
			1.4 V to 3.6 V	1.65 V to 5.5 V						
			3.6 V	0 V						
			0 V	5.5 V						
I _{CCA} + I _{CCB}	Combined supply current	V _I = V _{CCI} or GND I _O = 0	1.2 V	1.65 V to 5.5 V	3.5			10		μA
			1.4 V to 3.6 V	1.65 V to 5.5 V						
I _{CCZA}	High-impedance state, V _{CCA} supply current	V _I = V _{CCI} or GND I _O = 0, OE = GND	1.2 V	1.65 V to 5.5 V	0.05			5		μA
			1.4 V to 3.6 V	1.65 V to 5.5 V						
I _{CCZB}	High-impedance state, V _{CCB} supply current	V _I = V _{CCI} or GND I _O = 0, OE = GND	1.2 V	1.65 V to 5.5 V	3.3			5		μA
			1.4 V to 3.6 V	1.65 V to 5.5 V						
C _i	Input capacitance	OE	1.2 V to 3.6 V	1.65 V to 5.5 V	3			4		pF
C _{io}	Input-to-output internal capacitance	A port	1.2 V to 3.6 V	1.65 V to 5.5 V	5			6		pF
		B port	1.2 V to 3.6 V	1.65 V to 5.5 V	11			14		

(1) V_{CCI} is the supply voltage associated with the input port.

(2) V_{CCO} is the supply voltage associated with the output port.

6.6 Timing Requirements: $V_{CCA} = 1.2\text{ V}$

 $T_A = 25^\circ\text{C}$, $V_{CCA} = 1.2\text{ V}$

			$V_{CCB} = 1.8\text{ V}$			$V_{CCB} = 2.5\text{ V}$			$V_{CCB} = 3.3\text{ V}$			$V_{CCB} = 5\text{ V}$			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
Data rate			20			20			20			20			Mbps
t_w	Pulse duration	Data inputs	50			50			50			50			ns

6.7 Timing Requirements: $V_{CCA} = 1.5\text{ V} \pm 0.1\text{ V}$

 over recommended operating free-air temperature range, $V_{CCA} = 1.5\text{ V} \pm 0.1\text{ V}$ (unless otherwise noted)

			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
Data rate			40		40		40		40		Mbps
t_w	Pulse duration	Data inputs	25		25		25		25		ns

6.8 Timing Requirements: $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$

 over recommended operating free-air temperature range, $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$ (unless otherwise noted)

			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
Data rate			60		60		60		60		Mbps
t_w	Pulse duration	Data inputs	17		17		17		17		ns

6.9 Timing Requirements: $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$

 over recommended operating free-air temperature range, $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$ (unless otherwise noted)

			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
Data rate			100		100		100		Mbps
t_w	Pulse duration	Data inputs	10		10		10		ns

6.10 Timing Requirements: $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$

 over recommended operating free-air temperature range, $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted)

			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
Data rate			100		100		Mbps
t_w	Pulse duration	Data inputs	10		10		ns

6.11 Switching Characteristics: $V_{CCA} = 1.2\text{ V}$

 $T_A = 25^\circ\text{C}$, $V_{CCA} = 1.2\text{ V}$

PARAMETER	TEST CONDITIONS	$V_{CCB} = 1.8\text{ V}$			$V_{CCB} = 2.5\text{ V}$			$V_{CCB} = 3.3\text{ V}$			$V_{CCB} = 5\text{ V}$			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
t_{pd} Propagation delay time	A-to-B		6.9			5.7			5.3			5.5		ns
	B-to-A		7.4			6.4			6			5.8		
t_{en} Enable time	OE-to-A		1			1			1			1		μs
	OE-to-B		1			1			1			1		
t_{dis} Disable time	OE-to-A		18			15			14			14		ns
	OE-to-B		20			17			16			16		
t_{rA} , t_{fA} Input rise time, input fall time	A-port rise and fall times		4.2			4.2			4.2			4.2		ns
t_{rB} , t_{fB} Input rise time, input fall time	B-port rise and fall times		2.1			1.5			1.2			1.1		ns
$t_{SK(O)}$ Skew (time), output	Channel-to-channel skew		0.4			0.5			0.5			1.4		ns
Maximum data rate			20			20			20			20		Mbps

6.12 Switching Characteristics: $V_{CCA} = 1.5\text{ V} \pm 0.1\text{ V}$

over recommended operating free-air temperature range, $V_{CCA} = 1.5\text{ V} \pm 0.1\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd} Propagation delay time	A-to-B	1.4	12.9	1.2	10.1	1.1	10	0.8	9.9	ns
	B-to-A	0.9	14.2	0.7	12	0.4	11.7	0.3	13.7	
t_{en} Enable time	OE-to-A		1		1		1		1	μs
	OE-to-B		1		1		1		1	
t_{dis} Disable time	OE-to-A	5.9	31	5.7	25.9	5.6	23	5.7	22.4	ns
	OE-to-B	5.4	30.3	4.9	22.8	4.8	20	4.9	19.5	
t_{rA} , t_{fA} Input rise time, input fall time	A-port rise and fall times	1.4	5.1	1.4	5.1	1.4	5.1	1.4	5.1	ns
t_{rB} , t_{fB} Input rise time, input fall time	B-port rise and fall times	0.9	4.5	0.6	3.2	0.5	2.8	0.4	2.7	ns
$t_{SK(O)}$ Skew (time), output	Channel-to-channel skew		0.5		0.5		0.5		0.5	ns
Maximum data rate		40		40		40		40		Mbps

6.13 Switching Characteristics: $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$

 over recommended operating free-air temperature range, $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd} Propagation delay time	A-to-B	1.6	11	1.4	7.7	1.3	6.8	1.2	6.5	ns
	B-to-A	1.5	12	1.3	8.4	1	7.6	0.9	7.1	
t_{en} Enable time	OE-to-A		1		1		1		1	μs
	OE-to-B		1		1		1		1	
t_{dis} Disable time	OE-to-A	5.9	31	5.1	21.3	5	19.3	5	17.4	ns
	OE-to-B	5.4	30.3	4.4	20.8	4.2	17.9	4.3	16.3	
t_{rA}, t_{fA} Input rise time, input fall time	A-port rise and fall times	1	4.2	1.1	4.1	1.1	4.1	1.1	4.1	ns
t_{rB}, t_{fB} Input rise time, input fall time	B-port rise and fall times	0.9	3.8	0.6	3.2	0.5	2.8	0.4	2.7	ns
$t_{SK(O)}$ Skew (time), output	Channel-to-channel skew		0.5		0.5		0.5		0.5	ns
Maximum data rate		60		60		60		60		Mbps

6.14 Switching Characteristics: $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$

 over recommended operating free-air temperature range, $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd} Propagation delay time	A-to-B	1.1	6.3	1	5.2	0.9	4.7	ns
	B-to-A	1.2	6.6	1.1	5.1	0.9	4.4	
t_{en} Enable time	OE-to-A		1		1		1	μs
	OE-to-B		1		1		1	
t_{dis} Disable time	OE-to-A	5.1	21.3	4.6	15.2	4.6	13.2	ns
	OE-to-B	4.4	20.8	3.8	16	3.9	13.9	
t_{rA}, t_{fA} Input rise time, input fall time	A-port rise and fall times	0.8	3	0.8	3	0.8	3	ns
t_{rB}, t_{fB} Input rise time, input fall time	B-port rise and fall times	0.7	2.6	0.5	2.8	0.4	2.7	ns
$t_{SK(O)}$ Skew (time), output	Channel-to-channel skew		0.5		0.5		0.5	ns
Maximum data rate		100		100		100		Mbps

6.15 Switching Characteristics: $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$

over recommended operating free-air temperature range, $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CCB} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
		MIN	MAX	MIN	MAX	
t_{pd} Propagation delay time	A-to-B	0.9	4.7	0.8	4	ns
	B-to-A	1	4.9	0.9	3.8	
t_{en} Enable time	OE-to-A		1		1	μs
	OE-to-B		1		1	
t_{dis} Disable time	OE-to-A	4.6	15.2	4.3	12.1	ns
	OE-to-B	3.8	16	3.4	13.2	
t_{rA}, t_{fA} Input rise time, input fall time	A-port rise and fall times	0.7	2.5	0.7	2.5	ns
t_{rB}, t_{fB} Input rise time, input fall time	B-port rise and fall times	0.5	2.1	0.4	2.7	ns
$t_{SK(O)}$ Skew (time), output	Channel-to-channel skew		0.5		0.5	ns
Maximum data rate		100		100		Mbps

6.16 Operating Characteristics: $V_{CCA} = 1.2\text{ V to }1.5\text{ V}$, $V_{CCB} = 1.5\text{ V to }1.8\text{ V}$

 $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		V _{CCA} = 1.2 V, V _{CCB} =1.5 V			V _{CCA} = 1.2 V, V _{CCB} = 1.8 V			V _{CCA} = 1.5 V, V _{CCB} = 1.8 V			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
C _{pdA}	Power dissipation capacitance	C _L = 0 f = 10 MHz t _r = t _f = 1 ns OE = V _{CCA} (outputs enabled)	A-port input, B-port output	7.8			10			9			pF
			B-port input, A-port output	12			11			11			
C _{pdB}	Power dissipation capacitance		A-port input, B-port output	38.1			28			28			
			B-port input, A-port output	25.4			19			18			
C _{pdA}	Power dissipation capacitance	C _L = 0 f = 10 MHz t _r = t _f = 1 ns OE = GND (outputs disabled)	A-port input, B-port output	0.01			0.01			0.01			pF
			B-port input, A-port output	0.01			0.01			0.01			
C _{pdB}	Power dissipation capacitance		A-port input, B-port output	0.01			0.01			0.01			
			B-port input, A-port output	0.01			0.01			0.01			

6.17 Operating Characteristics: $V_{CCA} = 1.8\text{ V to }3.3\text{ V}$, $V_{CCB} = 1.8\text{ V to }5\text{ V}$

 $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		V _{CCA} = 1.8 V, V _{CCB} = 1.8 V			V _{CCA} = 2.5 V, V _{CCB} = 2.5 V			V _{CCA} = 2.5 V, V _{CCB} = 5 V			V _{CCA} = 3.3 V, V _{CCB} = 3.3 V to 5 V			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
C _{pdA}	Power dissipation capacitance	C _L = 0 f = 10 MHz t _r = t _f = 1 ns OE = V _{CCA} (outputs enabled)	A-port input, B-port output	8			8			8			9			pF
			B-port input, A-port output	11			11			11			11			
C _{pdB}	Power dissipation capacitance		A-port input, B-port output	28			29			29			29			
			B-port input, A-port output	18			19			21			22			
C _{pdA}	Power dissipation capacitance	C _L = 0 f = 10 MHz t _r = t _f = 1 ns OE = GND (outputs disabled)	A-port input, B-port output	0.01			0.01			0.01			0.01			pF
			B-port input, A-port output	0.01			0.01			0.01			0.01			
C _{pdB}	Power dissipation capacitance		A-port input, B-port output	0.01			0.01			0.01			0.03			
			B-port input, A-port output	0.01			0.01			0.01			0.04			

6.18 Typical Characteristics

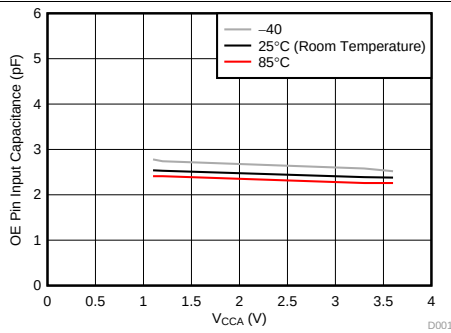


图 1. Input Capacitance for OE Pin (C_I) vs Power Supply (V_{CCA})

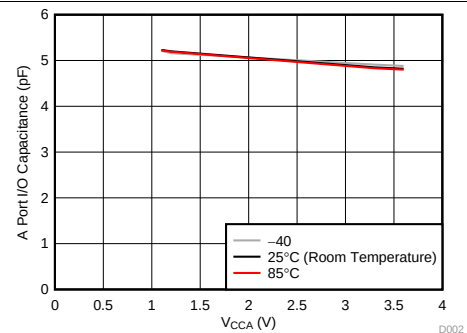


图 2. Capacitance for A port I/O Pins (C_{IO}) vs Power Supply (V_{CCA})

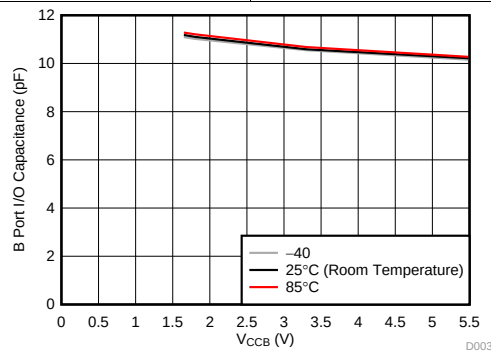


图 3. Capacitance for B Port I/O Pins (C_{IO}) vs Power Supply (V_{CCB})

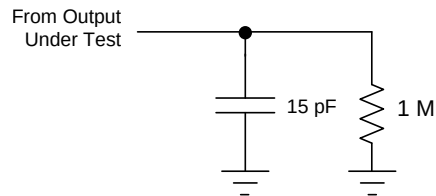
7 Parameter Measurement Information

Unless otherwise noted, all input pulses are supplied by generators that have the following characteristics:

- PRR 10 MHz
- $Z_O = 50\ \Omega$
- $dv/dt \geq 1\ \text{V/ns}$

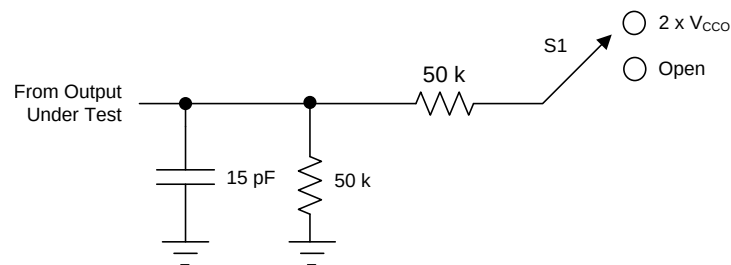
注

All parameters and waveforms are not applicable to all devices.



- (1) The outputs are measured one at a time, with one transition per measurement.

图 4. Load Circuit For Maximum Data Rate: Pulse Duration, Propagation Delay Output Rise, And Fall Time Measurement

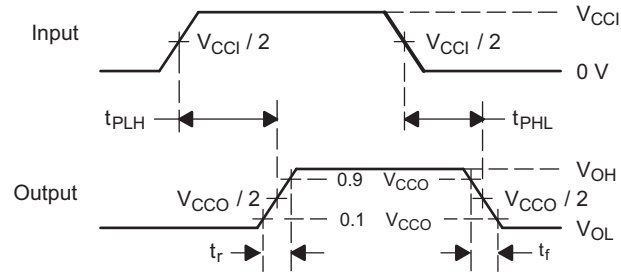


- (1) The outputs are measured one at a time, with one transition per measurement.

图 5. Load Circuit For Enable / Disable Time Measurement

表 1. Switch Position For Enable / Disable Time Measurement (See [Figure 5](#))

TEST	S1
t_{PZL}, t_{PLZ}	$2 \times V_{CCO}$
t_{PHZ}, t_{PZH}	Open



- (1) V_{CCI} is the V_{CC} associated with the input port.
- (2) V_{CCO} is the V_{CC} associated with the output port.
- (3) t_{PLH} and t_{PHL} are the same as t_{pd} .
- (4) The outputs are measured one at a time, with one transition per measurement.

图 6. Voltage Waveforms Propagation Delay Times

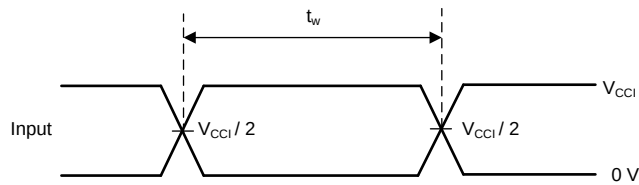


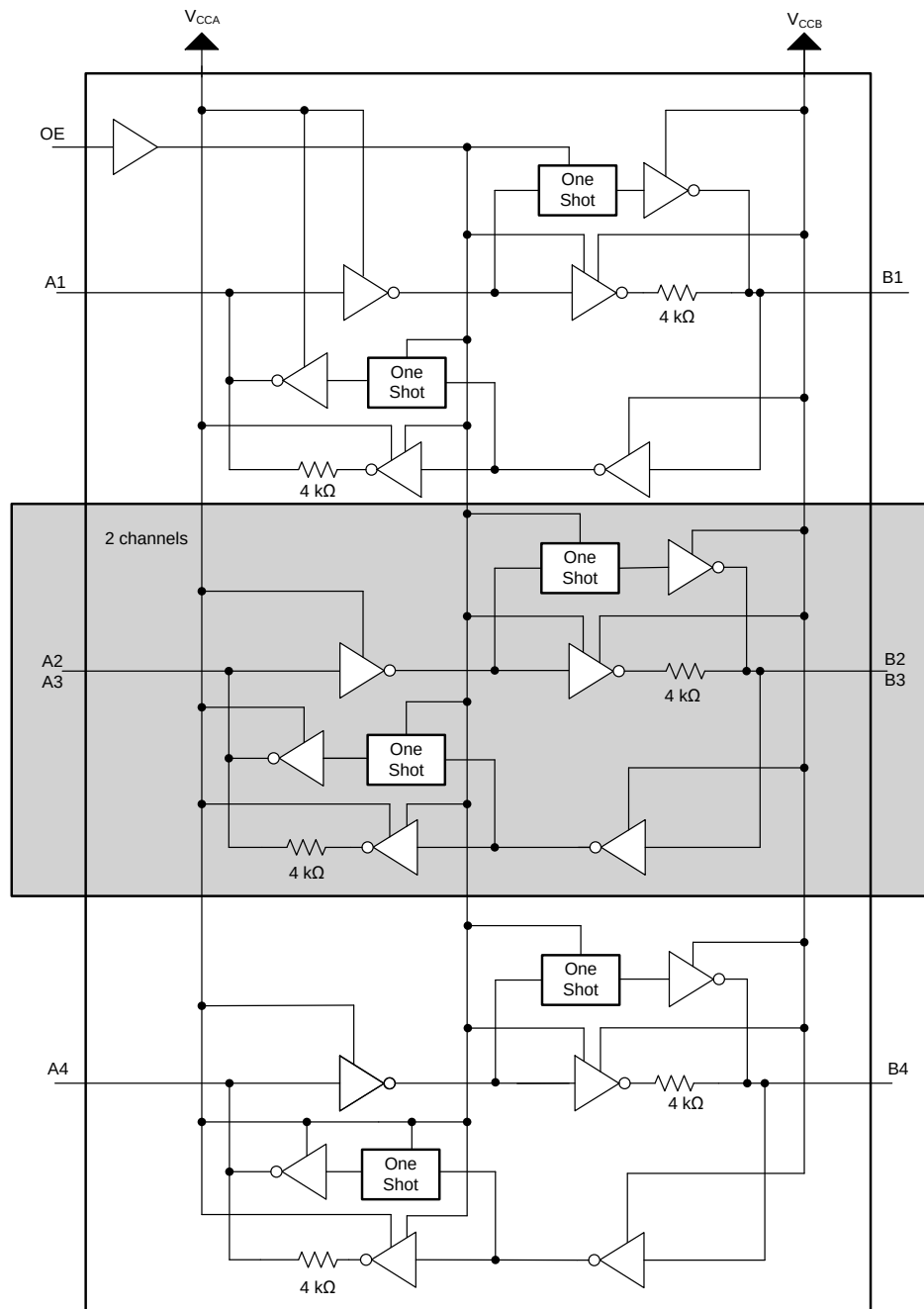
图 7. Voltage Waveforms Pulse Duration

8 Detailed Description

8.1 Overview

The TXB0104 device is a 4-bit, directionless voltage-level translator specifically designed for translating logic voltage levels. The A port is able to accept I/O voltages ranging from 1.2 V to 3.6 V, while the B port can accept I/O voltages from 1.65 V to 5.5 V. The device is a buffered architecture with edge-rate accelerators (one-shots) to improve the overall data rate. This device can only translate push-pull CMOS logic outputs. If for open-drain signal translation, please refer to TI's TXS010X products.

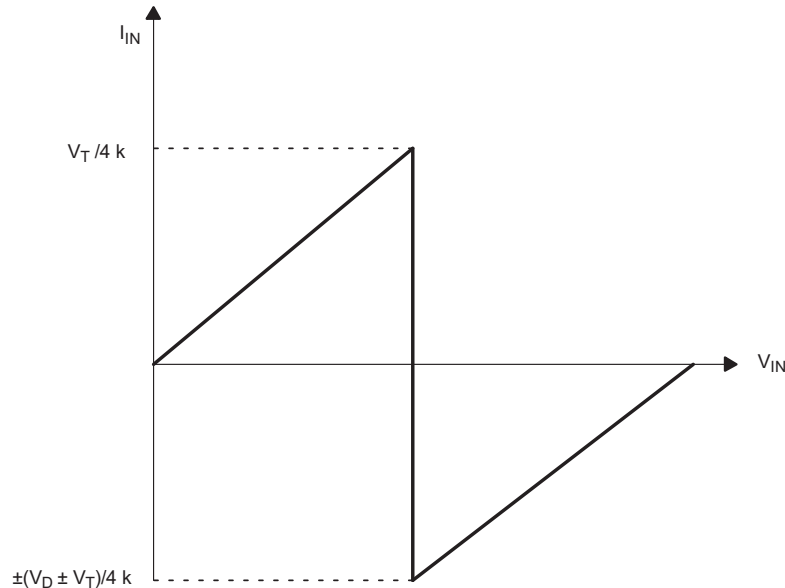
8.2 Functional Block Diagram



Feature Description (接下页)

8.3.2 Input Driver Requirements

Typical I_{IN} vs V_{IN} characteristics of the device are shown in 图 9. For proper operation, the device driving the data I/Os of the TXB0104 device must have drive strength of at least ± 2 mA.



- (1) V_T is the input threshold of the TXB0104 device, (typically $V_{CC} / 2$).
- (2) V_D is the supply voltage of the external driver.

图 9. Typical I_{IN} vs V_{IN} Curve

8.3.3 Output Load Considerations

TI recommends careful PCB layout practices with short PCB trace lengths to avoid excessive capacitive loading and to ensure that proper O.S. triggering takes place. PCB signal trace-lengths must be kept short enough such that the round trip delay of any reflection is less than the one-shot duration. This improves signal integrity by ensuring that any reflection sees a low impedance at the driver. The O.S. circuits have been designed to stay on for approximately 10 ns. The maximum capacitance of the lumped load that can be driven also depends directly on the one-shot duration. With very heavy capacitive loads, the one-shot can time-out before the signal is driven fully to the positive rail. The O.S. duration has been set to best optimize trade-offs between dynamic ICC, load driving capability, and maximum bit-rate considerations. Both PCB trace length and connectors add to the capacitance that the device output sees, so it is recommended that this lumped-load capacitance be considered to avoid O.S. retriggering, bus contention, output signal oscillations, or other adverse system-level affects.

Feature Description (接下页)

8.3.4 Enable and Disable

The TXB0104 device has an OE input that is used to disable the device by setting OE = low, which places all I/Os in the high-impedance (Hi-Z) state. The disable time (t_{dis}) indicates the delay between when OE goes low and when the outputs actually get disabled (Hi-Z). The enable time (t_{en}) indicates the amount of time the user must allow for the one-shot circuitry to become operational after OE is taken high.

8.3.5 Pullup or Pulldown Resistors on I/O Lines

The device is designed to drive capacitive loads of up to 70 pF. The output drivers of the TXB0104 device have low dc drive strength. If pullup or pulldown resistors are connected externally to the data I/Os, their values must be kept higher than 50 k Ω to ensure that they do not contend with the output drivers of the TXB0104 device.

For the same reason, the TXB0104 device must not be used in applications such as I²C or 1-Wire where an open-drain driver is connected on the bidirectional data I/O. For these applications, use a device from the TI TXS01xx series of level translators.

8.4 Device Functional Modes

The device has two functional modes, enabled and disabled. To disable the device, set the OE input to low, which places all I/Os in a high impedance state. Setting the OE input to high will enable the device.

9 Application and Implementation

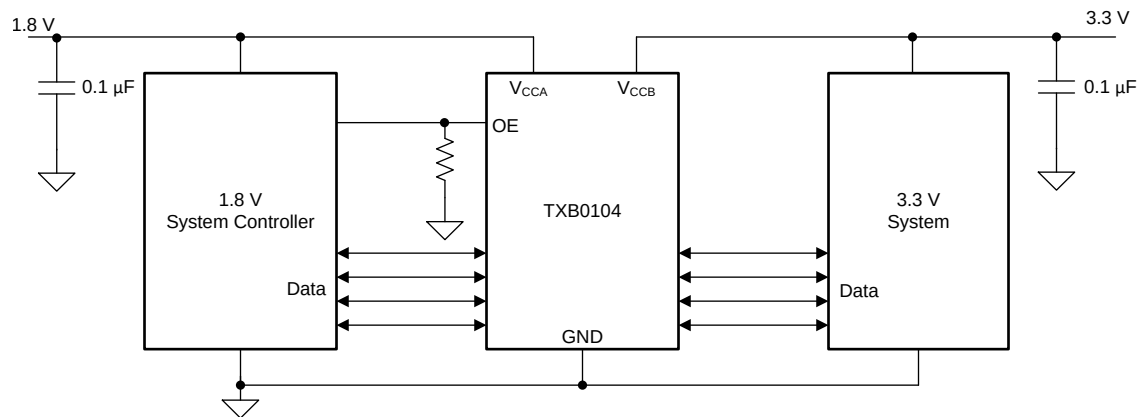
注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers must validate and test their design implementation to confirm system functionality.

9.1 Application Information

The TXB0104 device can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. It can only translate push-pull CMOS logic outputs. If for open-drain signal translation, please refer to TI TXS010X products. Any external pulldown or pullup resistors are recommended larger than 50 k Ω .

9.2 Typical Application



9.2.1 Design Requirements

For this design example, use the parameters listed in 表 2. And make sure the $V_{CCA} \leq V_{CCB}$.

表 2. Design Parameters

DESIGN PARAMETERS	EXAMPLE VALUE
Input voltage range	1.2 V to 3.6 V
Output voltage range	1.65 V to 5.5 V

9.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- Input voltage range
 - Use the supply voltage of the device that is driving the TXB0104 device to determine the input voltage range. For a valid logic high, the value must exceed the V_{IH} of the input port. For a valid logic low, the value must be less than the V_{IL} of the input port.
- Output voltage range
 - Use the supply voltage of the device that the device is driving to determine the output voltage range.
 - External pullup or pulldown resistors are not recommended. If mandatory, it is recommended that the value must be larger than 50 k Ω .
- An external pulldown or pullup resistor decreases the output V_{OH} and V_{OL} . Use the below equations to draft estimate the V_{OH} and V_{OL} as a result of an external pulldown and pullup resistor.

$$V_{OH} = V_{CCX} \times R_{PD} / (R_{PD} + 4.5 \text{ k}\Omega)$$

$$V_{OL} = V_{CCX} \times 4.5 \text{ k}\Omega / (R_{PU} + 4.5 \text{ k}\Omega)$$

Where

- V_{CCX} is the output port supply voltage on either V_{CCA} or V_{CCB}
- R_{PD} is the value of the external pull down resistor
- R_{PU} is the value of the external pull up resistor
- 4.5 k Ω is the counting the variation of the serial resistor 4 k Ω in the I/O line.

9.2.3 Application Curves

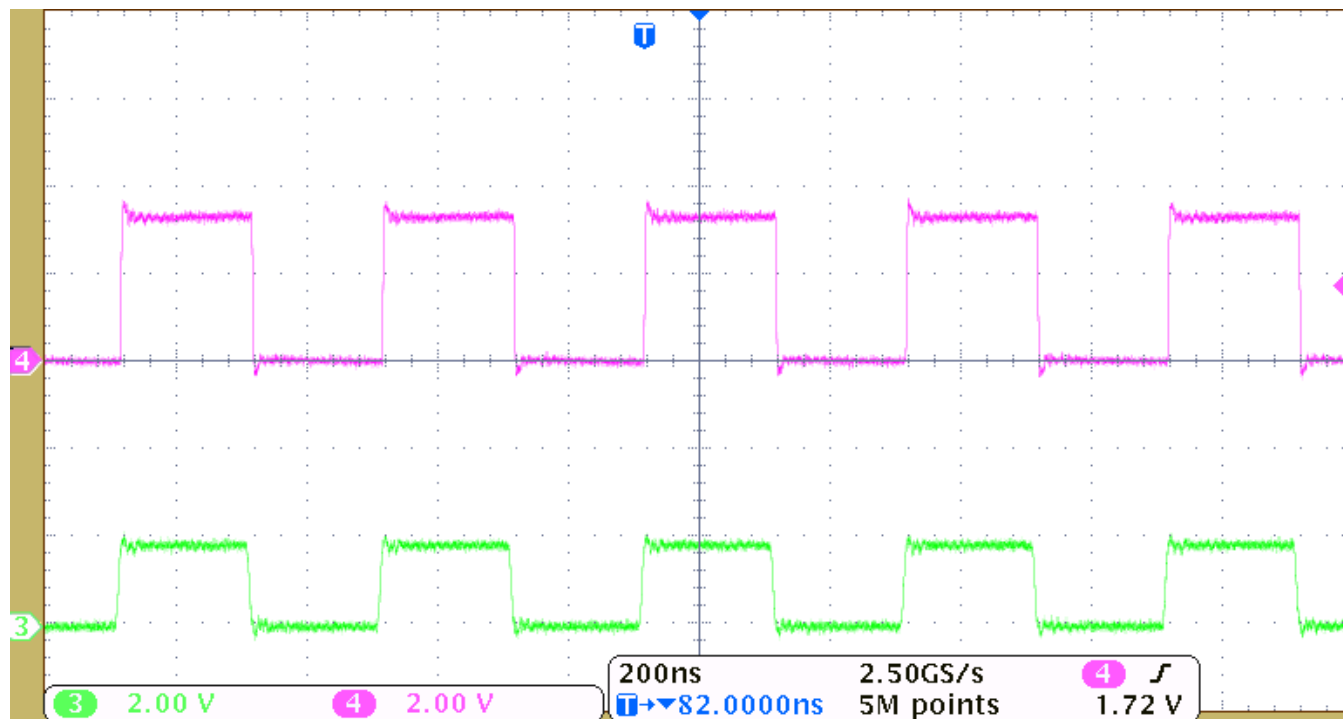


图 10. Level-Translation of a 2.5-MHz Signal

10 Power Supply Recommendations

During operation, ensure that $V_{CCA} \leq V_{CCB}$ at all times. During power-up sequencing, $V_{CCA} \geq V_{CCB}$ does not damage the device, so any power supply can be ramped up first. The device has circuitry that disables all output ports when either V_{CC} is switched off ($V_{CCA/B} = 0$ V). The output-enable (OE) input circuit is designed so that it is supplied by V_{CCA} and when the (OE) input is low, all outputs are placed in the high-impedance state. To ensure the high-impedance state of the outputs during power up or power down, the OE input pin must be tied to GND through a pulldown resistor and must not be enabled until V_{CCA} and V_{CCB} are fully ramped and stable. The minimum value of the pulldown resistor to ground is determined by the current-sourcing capability of the driver.

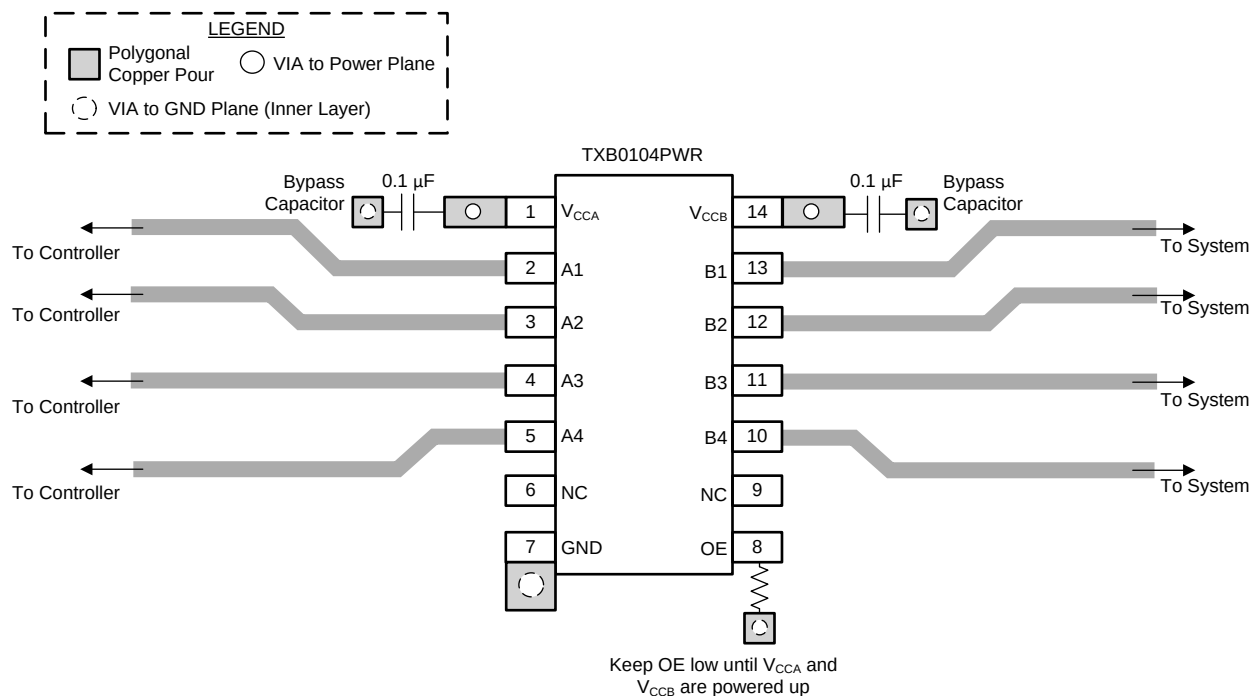
11 Layout

11.1 Layout Guidelines

To ensure reliability of the device, following common printed-circuit board layout guidelines is recommended.

- Bypass capacitors must be used on power supplies, and must be placed as close as possible to the V_{CCA} , V_{CCB} pin and GND pin.
- Short trace-lengths must be used to avoid excessive loading.
- PCB signal trace-lengths must be kept short enough so that the round-trip delay of any reflection is less than the one-shot duration, approximately 10 ns, ensuring that any reflection encounters low impedance at the source driver.

11.2 Layout Example



12 器件和文档支持

12.1 接收文档更新通知

如需接收文档更新通知，请访问 www.ti.com.cn 网站上的器件产品文件夹。单击右上角的通知我 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

12.2 社区资源

下列链接提供到 TI 社区资源的连接。链接的内容由各个分销商“按照原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

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设计支持 TI 参考设计支持 可帮助您快速查找有帮助的 E2E 论坛、设计支持工具以及技术支持的联系信息。

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ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

12.5 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

13 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。如需获取此数据表的浏览器版本，请参阅左侧的导航栏。

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
HPA01164RUTR	ACTIVE	UQFN	RUT	12	3000	RoHS & Green	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	(2KR, 2KV)	Samples
TXB0104D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TXB0104	Samples
TXB0104DG4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TXB0104	Samples
TXB0104DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TXB0104	Samples
TXB0104DRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TXB0104	Samples
TXB0104NMNR	ACTIVE	NFBGA	NMN	12	2500	RoHS & Green	SNAGCU	Level-2-260C-1 YEAR	-40 to 85	2AQW	Samples
TXB0104PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	YE04	Samples
TXB0104PWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	YE04	Samples
TXB0104RGYR	ACTIVE	VQFN	RGY	14	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	YE04	Samples
TXB0104RGYRG4	ACTIVE	VQFN	RGY	14	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	YE04	Samples
TXB0104RUTR	ACTIVE	UQFN	RUT	12	3000	RoHS & Green	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	(2KR, 2KV)	Samples
TXB0104YZTR	ACTIVE	DSBGA	YZT	12	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	(2K, 2K7)	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- ⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- ⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- ⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- ⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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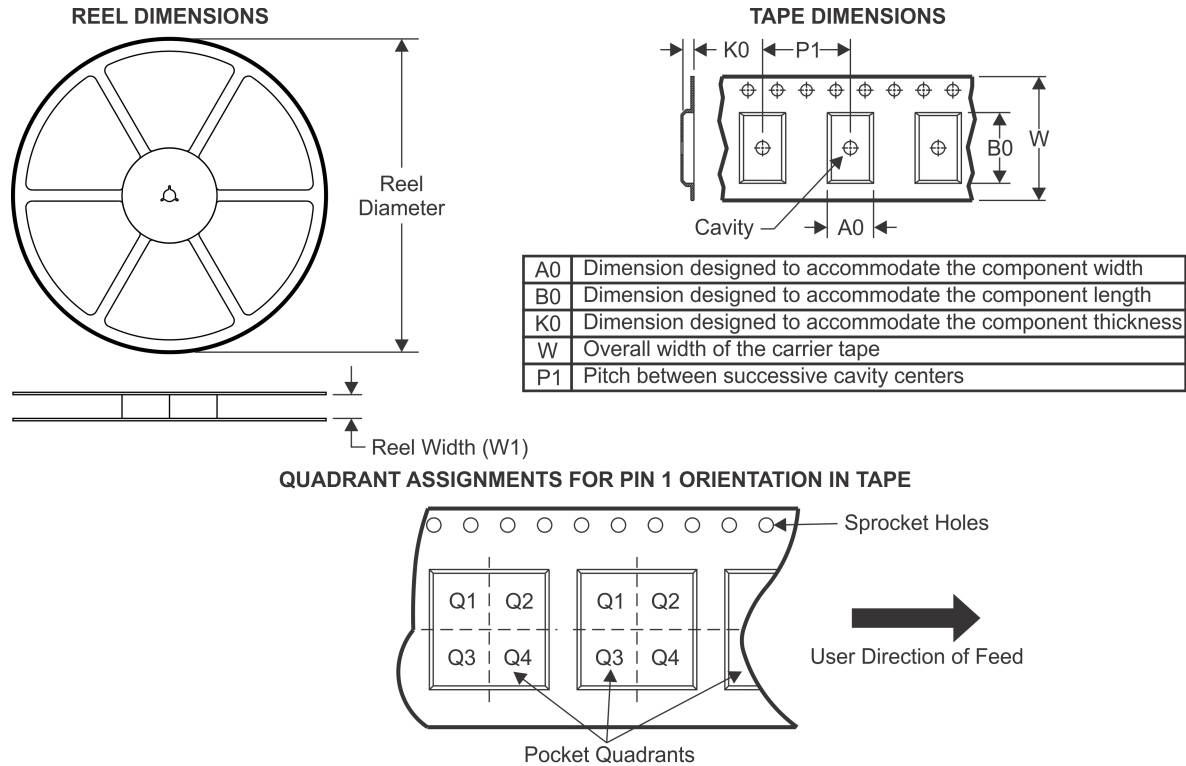
OTHER QUALIFIED VERSIONS OF TXB0104 :

- Automotive : [TXB0104-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

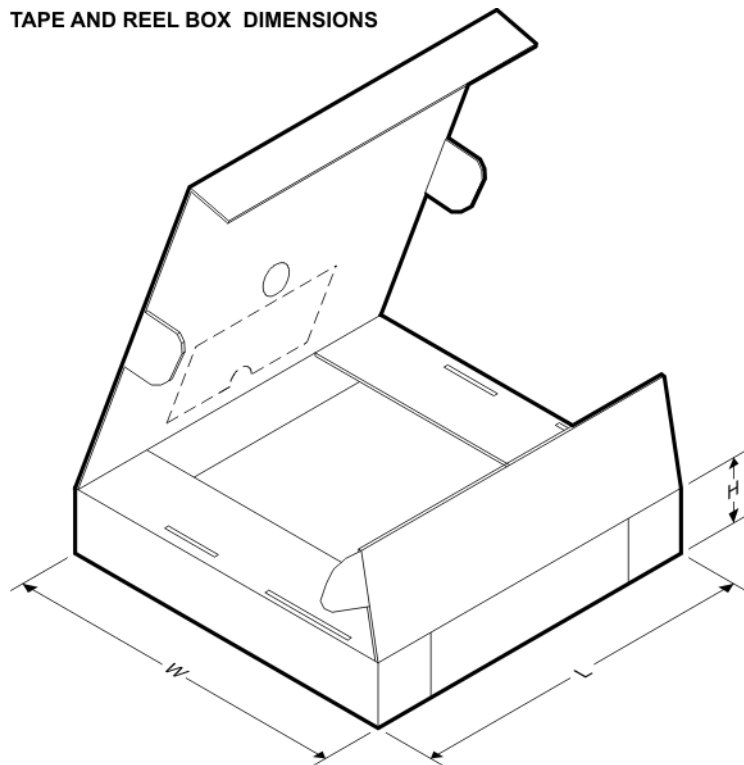
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TXB0104DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TXB0104NMNR	NFBGA	NMN	12	2500	180.0	8.4	2.3	2.8	1.15	4.0	8.0	Q2
TXB0104PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TXB0104RGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1
TXB0104RUTR	UQFN	RUT	12	3000	180.0	8.4	1.95	2.3	0.75	4.0	8.0	Q1
TXB0104RUTR	UQFN	RUT	12	3000	180.0	9.5	1.9	2.2	0.7	4.0	8.0	Q1
TXB0104YZTR	DSBGA	YZT	12	3000	180.0	8.4	1.49	1.99	0.75	4.0	8.0	Q2

TAPE AND REEL BOX DIMENSIONS

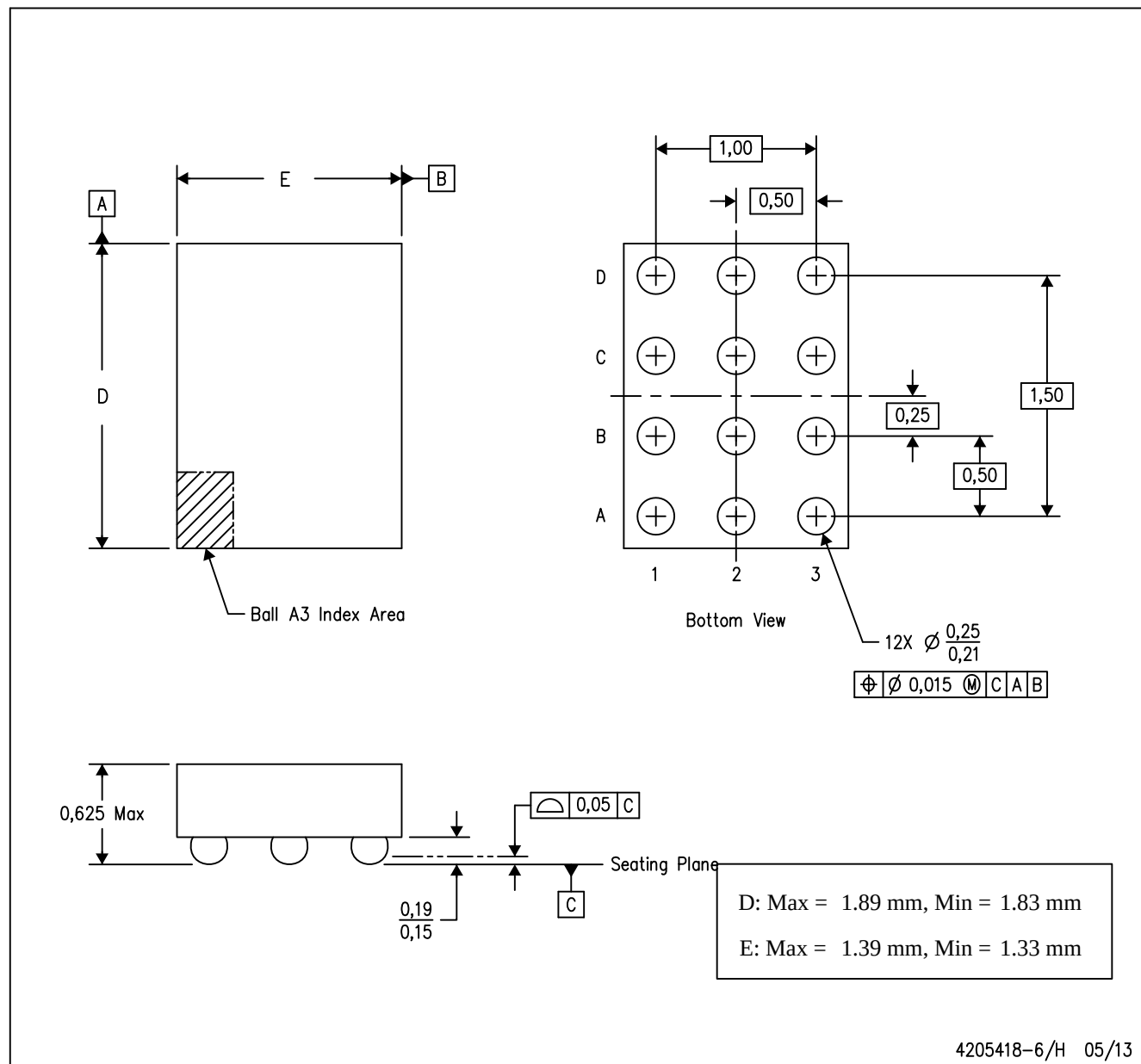


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TXB0104DR	SOIC	D	14	2500	853.0	449.0	35.0
TXB0104NMNR	NFBGA	NMN	12	2500	210.0	185.0	35.0
TXB0104PWR	TSSOP	PW	14	2000	853.0	449.0	35.0
TXB0104RGYR	VQFN	RGY	14	3000	853.0	449.0	35.0
TXB0104RUTR	UQFN	RUT	12	3000	202.0	201.0	28.0
TXB0104RUTR	UQFN	RUT	12	3000	189.0	185.0	36.0
TXB0104YZTR	DSBGA	YZT	12	3000	182.0	182.0	20.0

YZT (R-XBGA-N12)

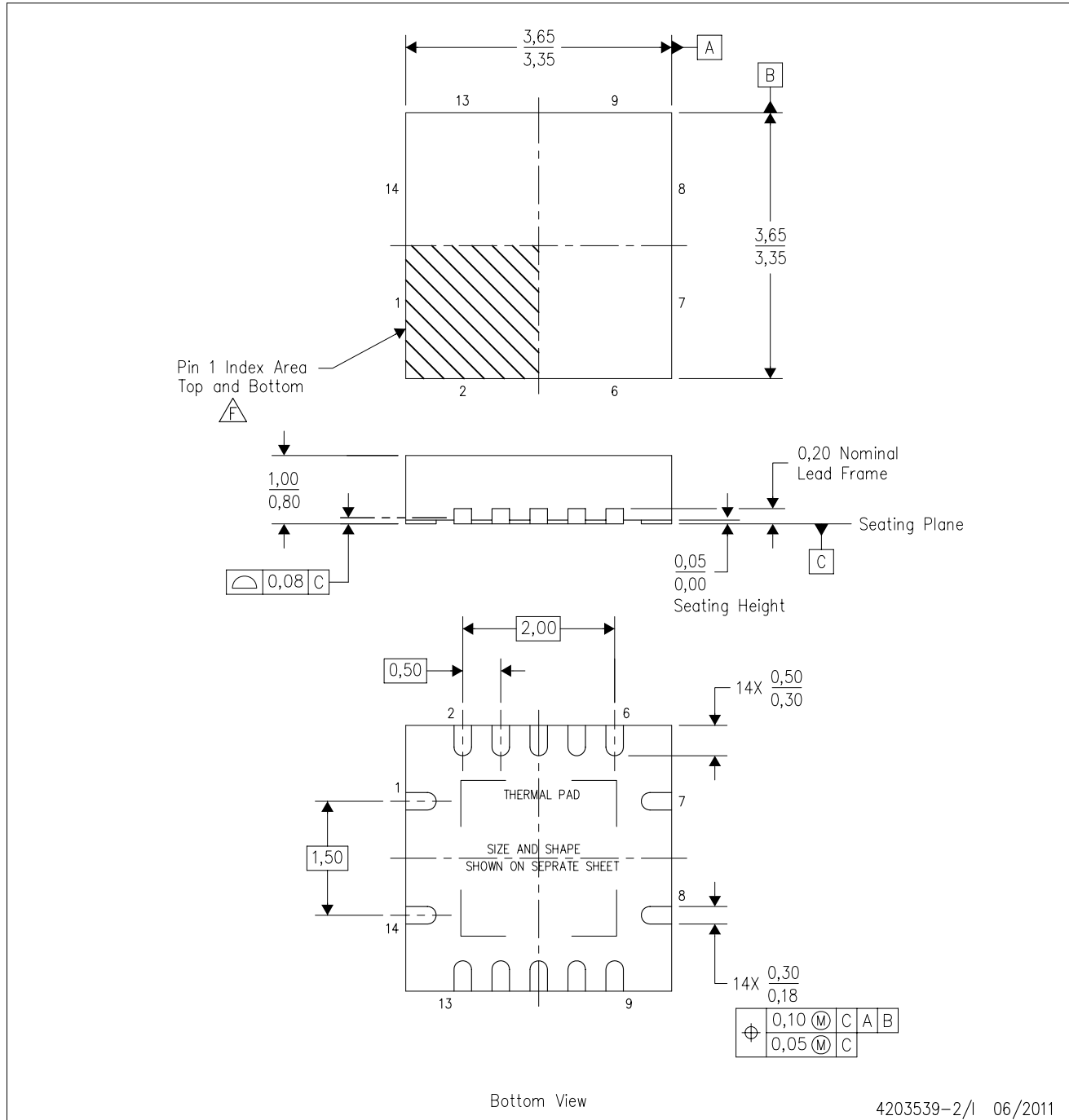
(CUSTOM) DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



4203539-2/I 06/2011

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - Package complies to JEDEC MO-241 variation BA.

RGY (S-PVQFN-N14)

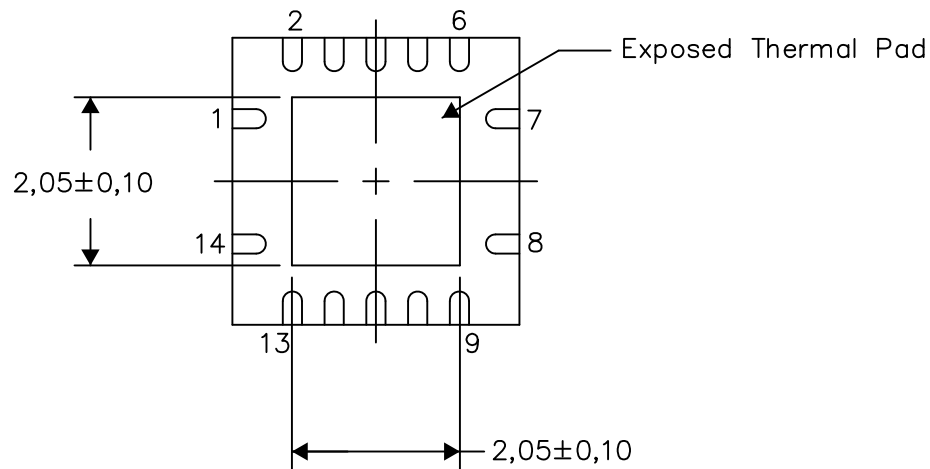
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

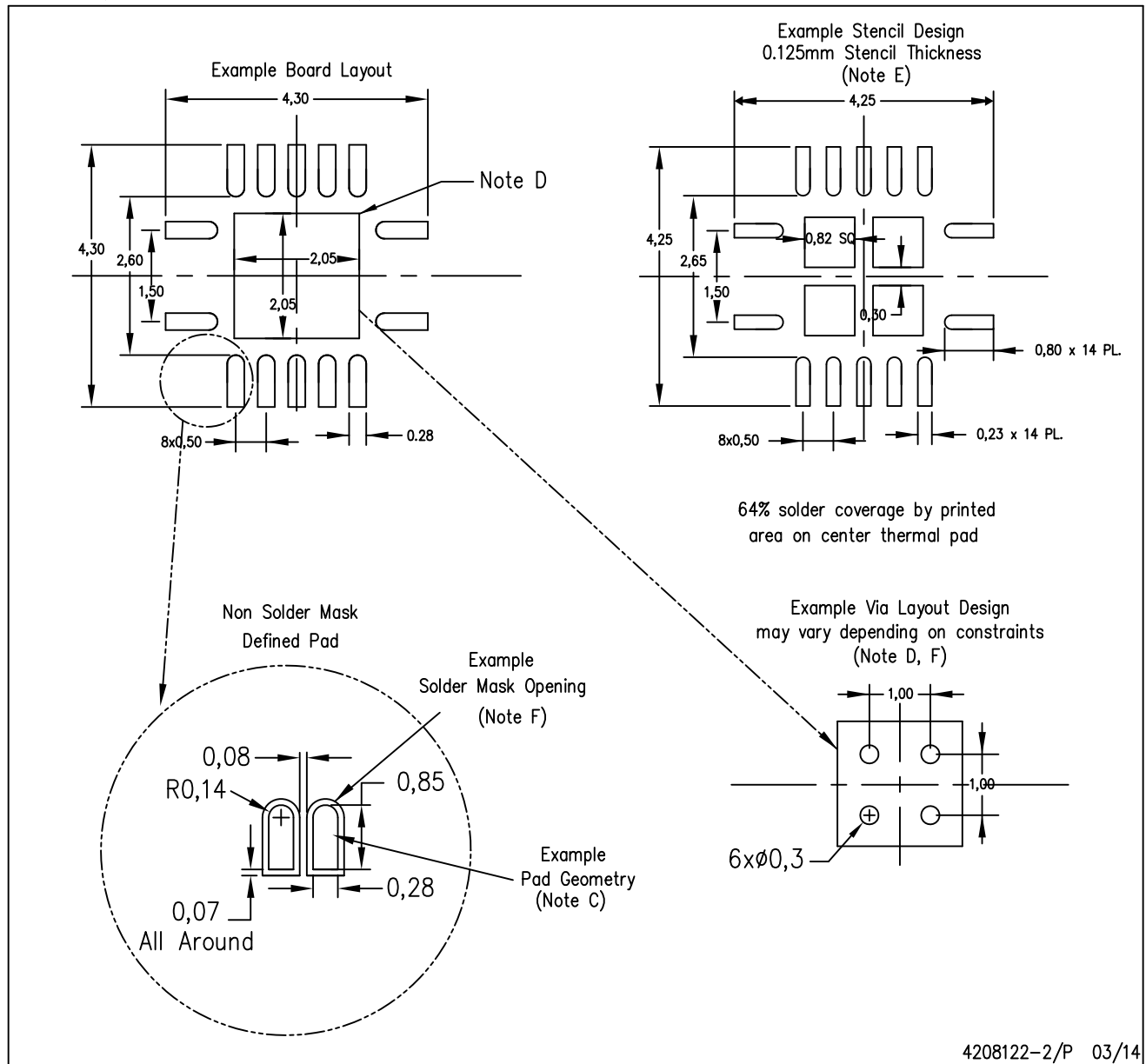
Exposed Thermal Pad Dimensions

4206353-2/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD

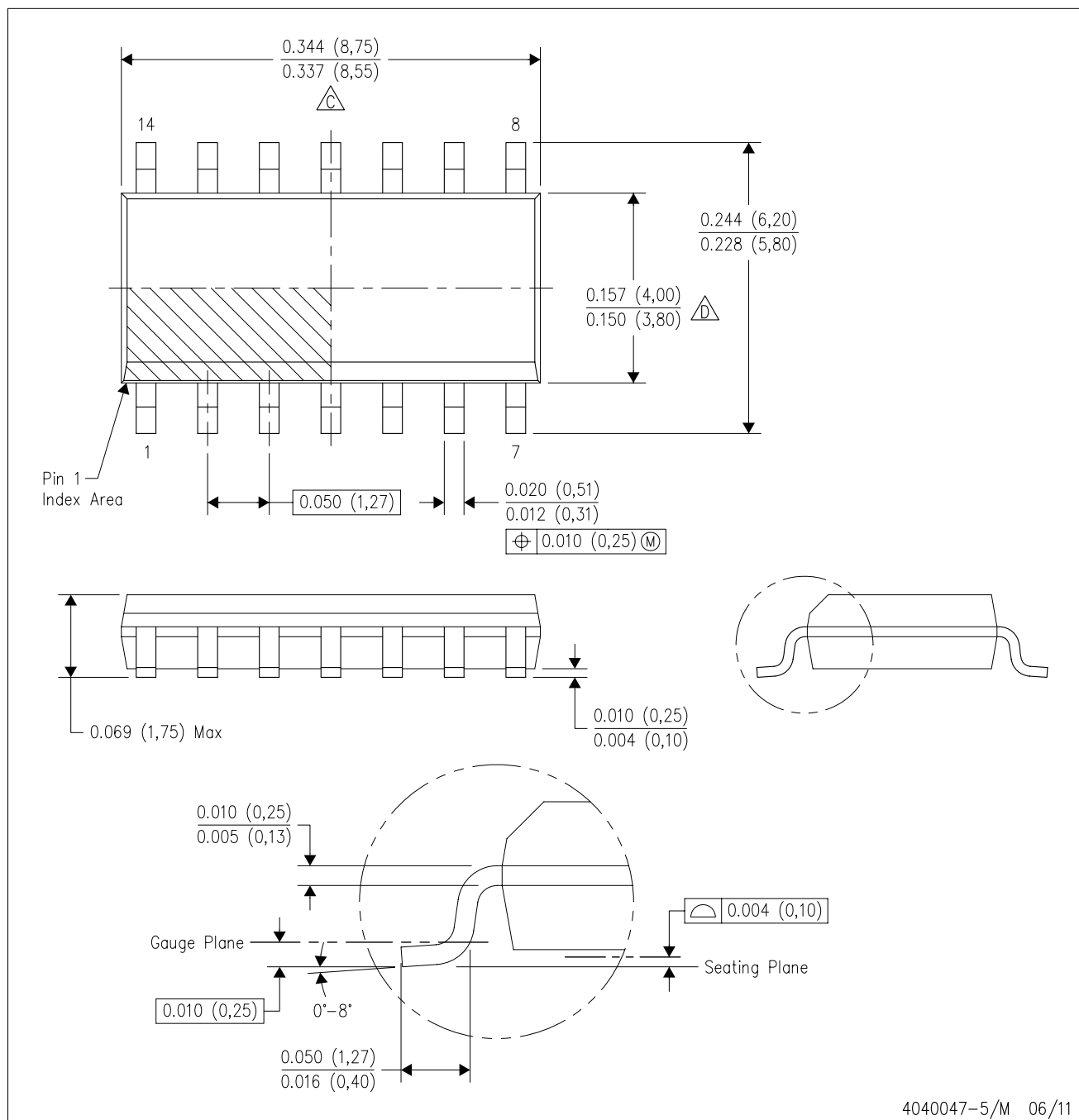


4208122-2/P 03/14

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



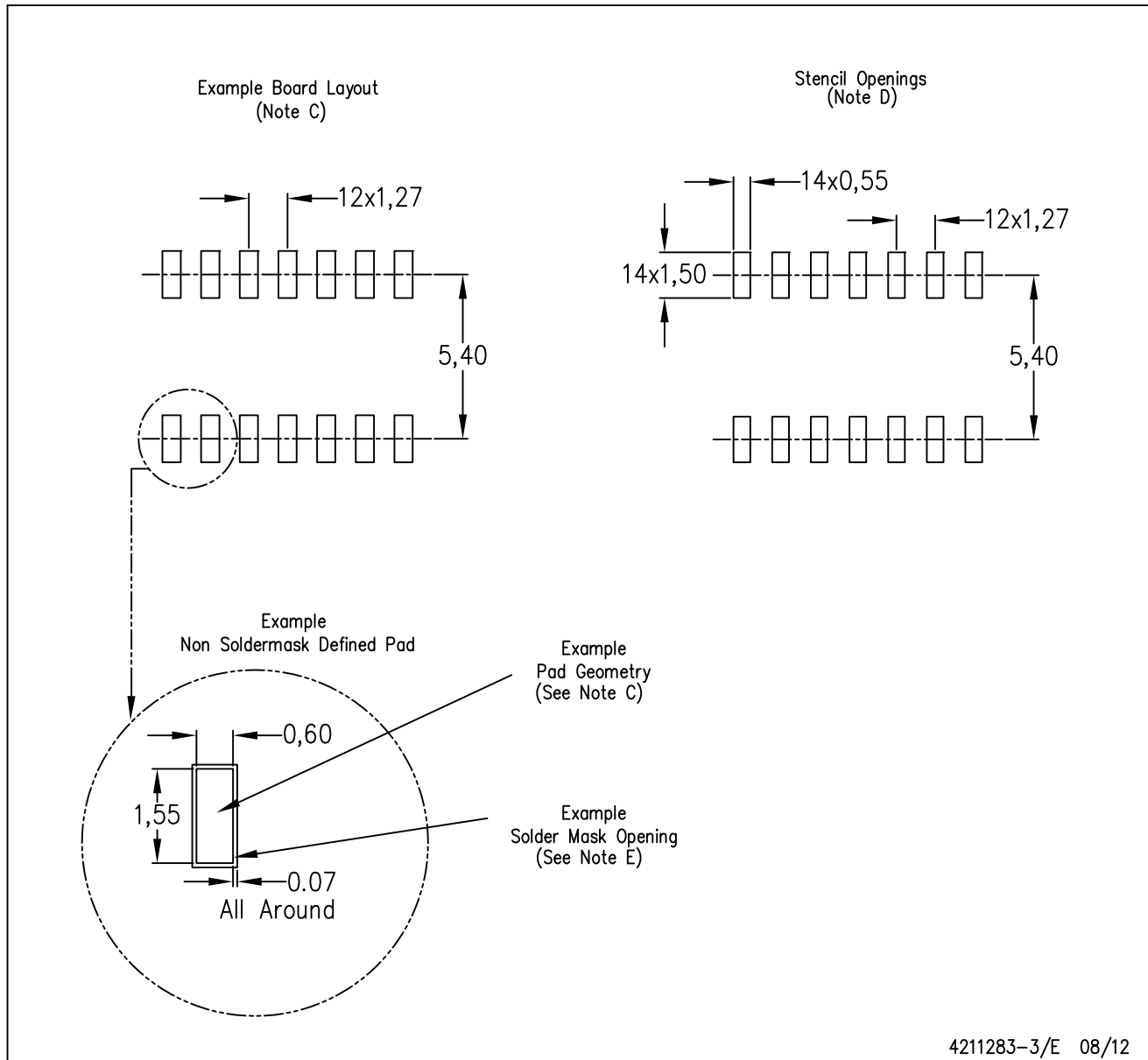
4040047-5/M 06/11

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

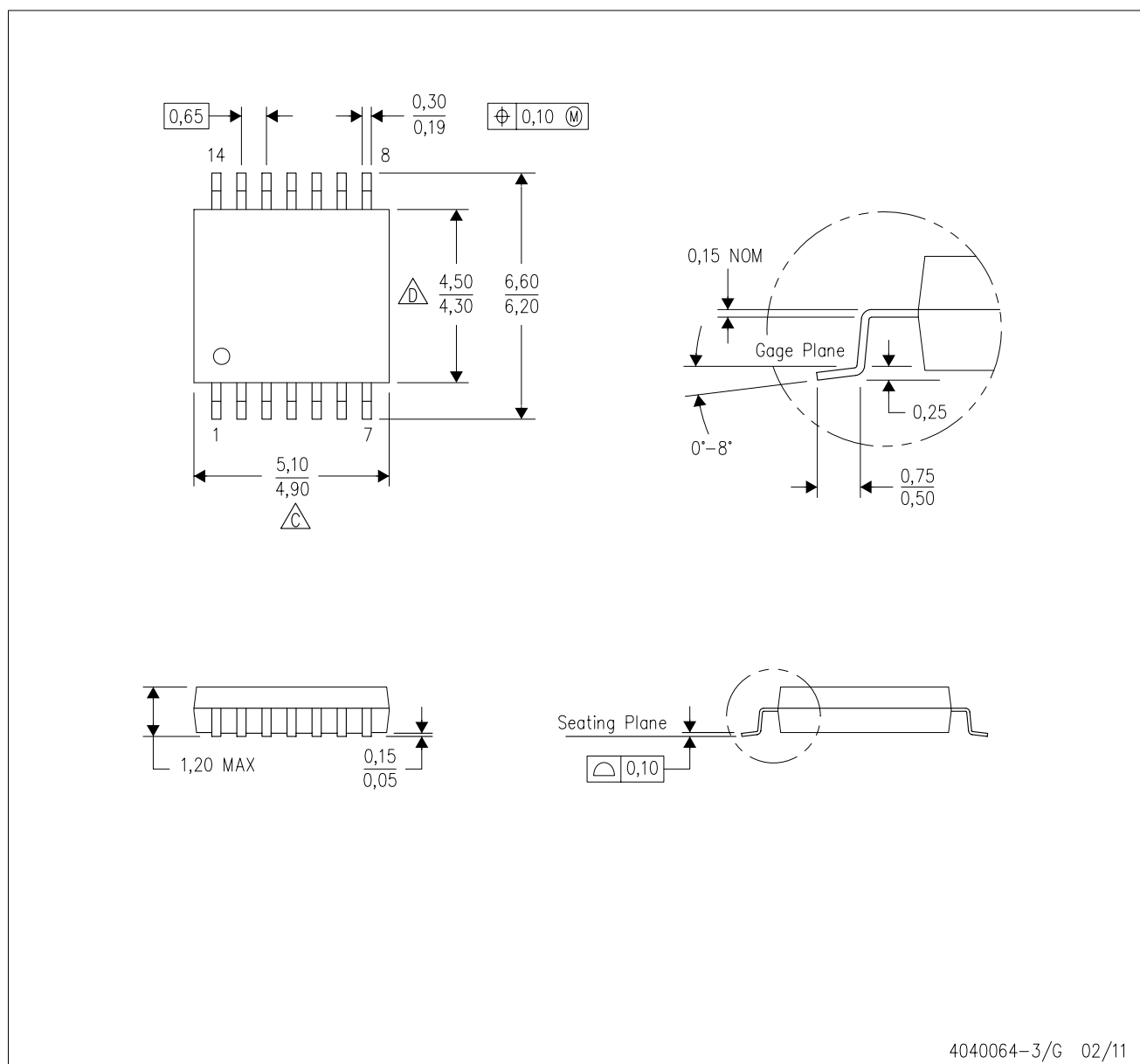
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

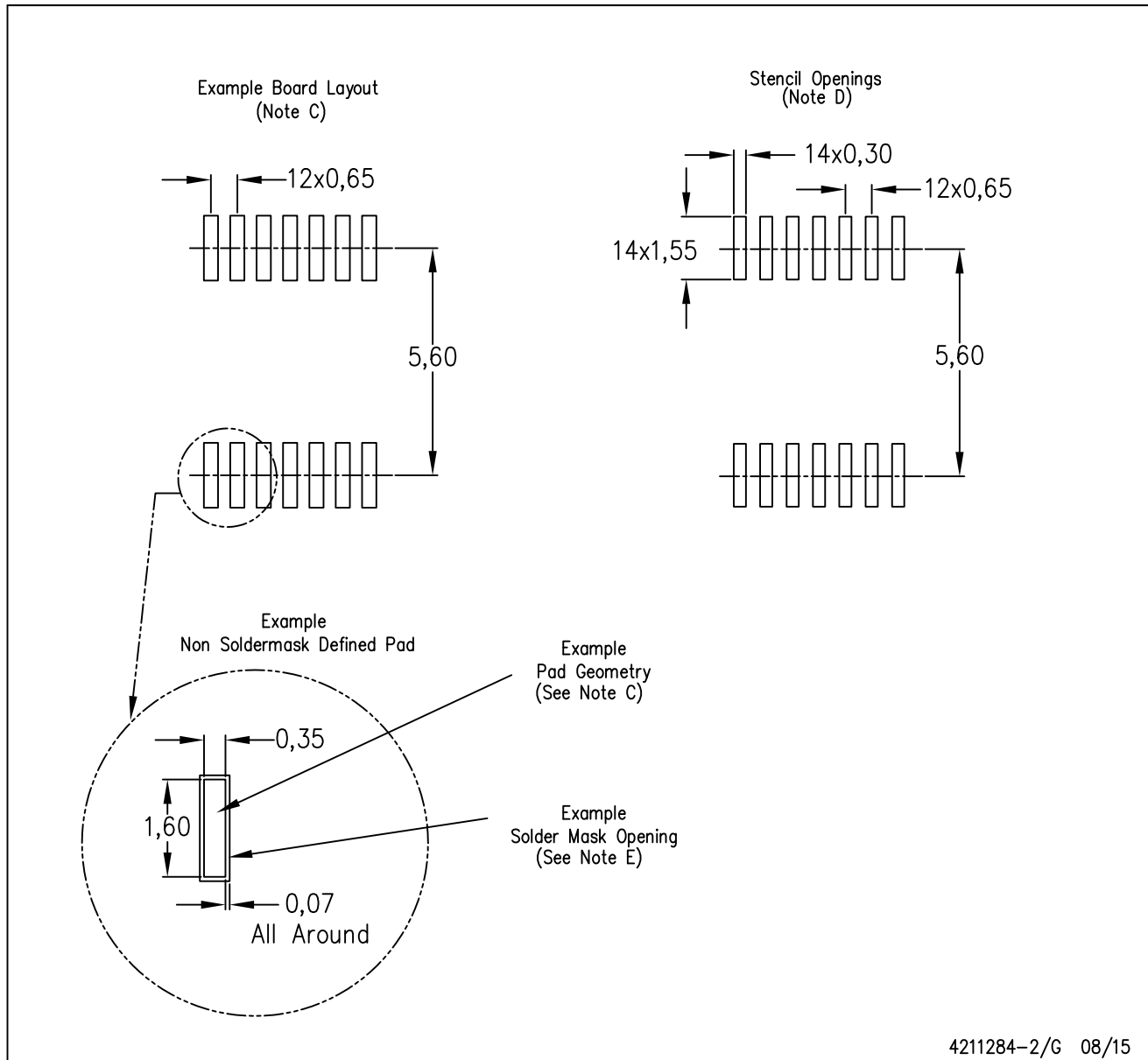


4040064-3/G 02/11

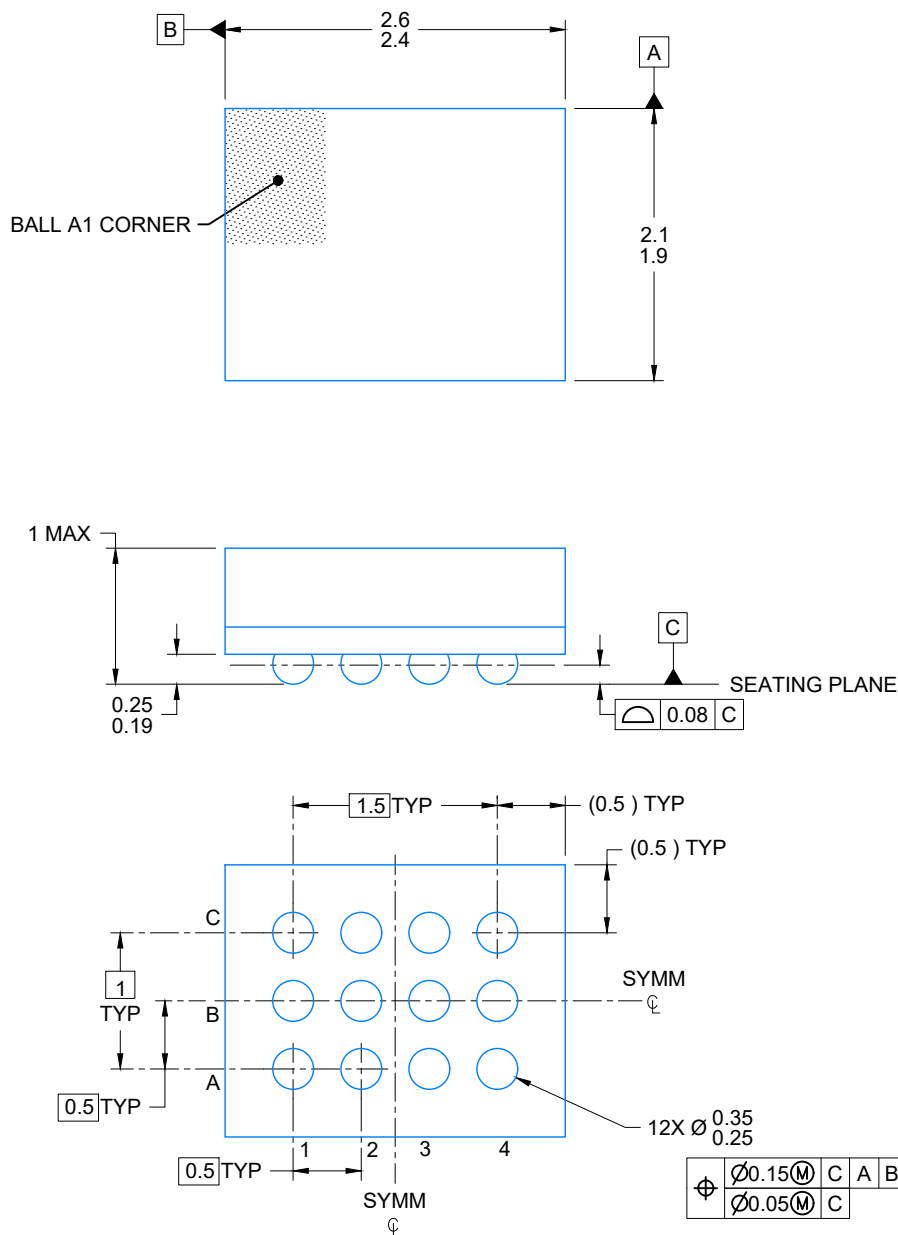
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

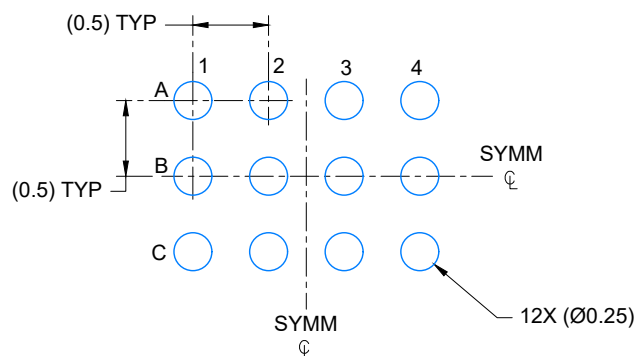


4225768/A 03/2020

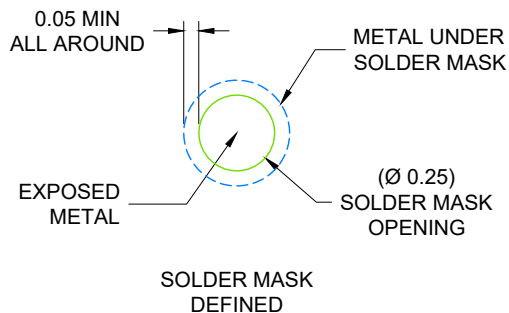
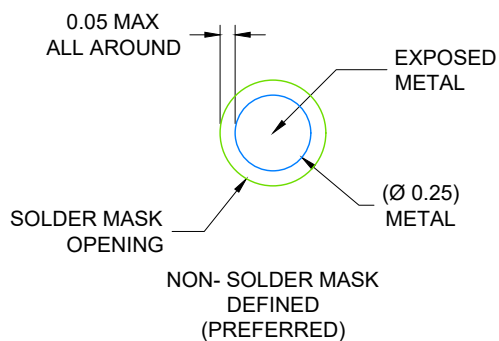
NOTES:

NanoFree is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
SCALE: 20X

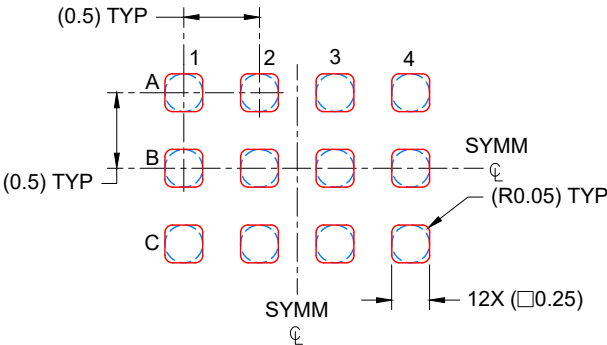


SOLDER MASK DETAILS
NOT TO SCALE

4225768/A 03/2020

NOTES: (continued)

- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. Refer to Texas Instruments Literature number SNVA009 (www.ti.com/lit/snva009).



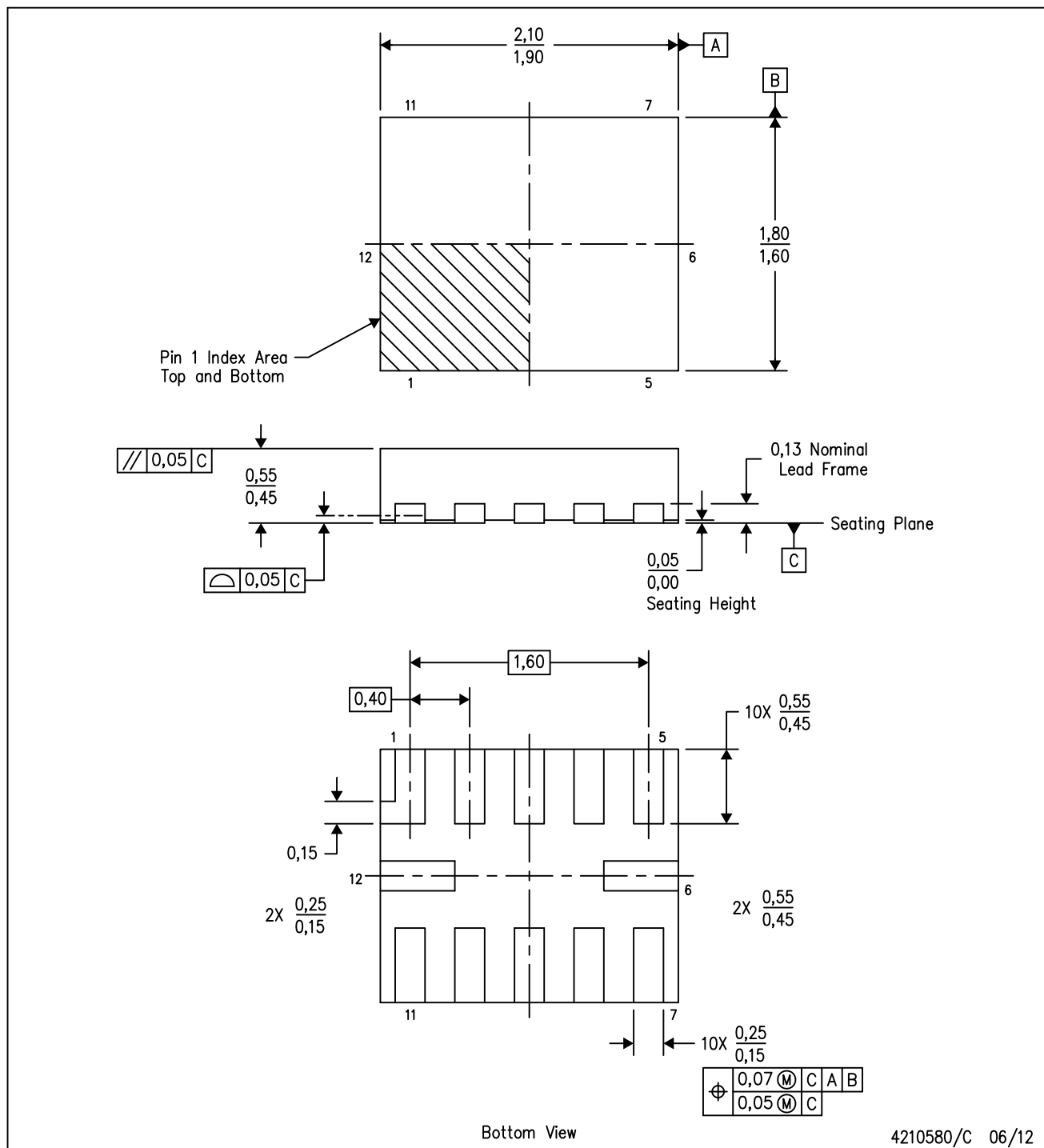
SOLDER PASTE EXAMPLE
BASED ON 0.100 mm THICK STENCIL
SCALE: 20X

NOTES: (continued)

- 4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

RUT (R-PUQFN-N12)

PLASTIC QUAD FLATPACK NO-LEAD

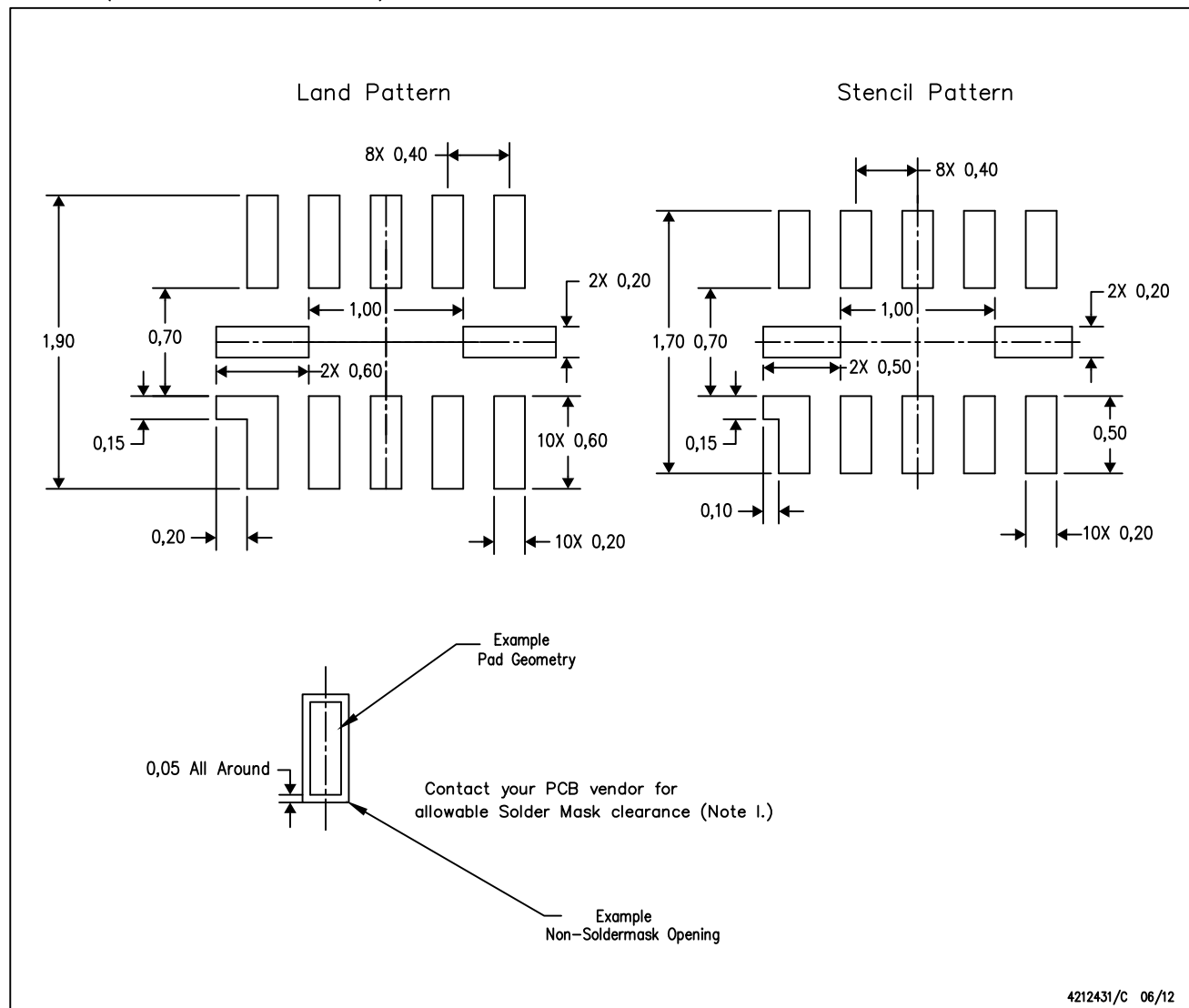


4210580/C 06/12

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.

RUT (R-PUQFN-N12)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
 - Maximum stencil thickness 0,1016 mm (4 mils). All linear dimensions are in millimeters.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Over-printing land for larger area ratio is not advised due to land width and bridging potential. Exercise extreme caution.
 - Suggest stencils cut with lasers such as Fiber Laser that produce the greatest positional accuracy.
 - Component placement force should be minimized to prevent excessive paste block deformation.

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